

Product/Process Change Notice - PCN 13_0331 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: Change of Bump Site, Bump and Laminate Material for ADSP-TS20xS Products

Publication Date: 29-Jan-2014

Effectivity Date: 29-Apr-2014 (the earliest date that a customer could expect to receive changed material)

Description:

Initial Release				

Description Of Change

- 1) Bumping site is changing from IBM to ADI qualified subcontractor, Amkor, Taiwan.
- 2) Bump material is changing from high-lead(Pb) 97Pb/3Sn to lead(Pb)-free 98.2Sn/1.9Ag.
- 3) Under Bump Metalization (UBM) is changing from Ni to TiW/Cu/Ni.
- 4) Core material for laminate is changing from SLC-679F to SLC-679FG(R).

All bumping changes are internal to the package and do not affect the external solder ball materials.

Reason For Change

Changing bumping site and materials to conform to industry best practices for Pb-Free bumping.

ADI's assembly subcontractors manufacture our products using Analog Devices specified manufacturing flows, process controls and monitors. This assures that our customers receive the same level of quality and reliability on products they receive from different manufacturing locations.

Impact of the change (positive or negative) on fit, form, function & reliability

Changes will have no impact on form, fit, functionality or reliability of the ADSP-TS20xS products.

Summary of Supporting Information

Qualification will be performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Plan Summary.

Comments

Samples will be available in February 2014.

Supporting Documents

Attachment 1: Type: Qualification Plan Summary
ADI_PCN_13_0331_Rev_-_ADSP-TS20xQualPlan.docx

	For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative					
Americas:	PCN_Americas@analog.com	Europe:	PCN_Europe@analog.com	Japan:	PCN_Japan@analog.com	
				Rest of Asia:	PCN_ROA@analog.com	

Appendix A - Affected ADI Models					
Added Parts On This Revision - Product Family / Model Number (12)					
ADSP-TS201S / AD90813	ADSP-TS201S / AD91146	ADSP-TS201S / ADSP-TS201SABP-050	ADSP-TS201S / ADSP-TS201SABP-060	ADSP-TS201S / ADSP-TS201SABPZ050	
ADSP-TS201S / ADSP-TS201SABPZ060	ADSP-TS201S / ADSP-TS201SYBP-050	ADSP-TS201S / ADSP-TS201SYBPZ050	ADSP-TS202S / ADSP-TS202SABPZ050	ADSP-TS203S / ADSP-TS203SABP-050	
ADSP-TS203S / ADSP-TS203SABPZ050	ADSP-TS203S / ADSP-TS203SBBPZ050				

Appendix B - Revision History						
Rev	Rev Publish Date Effectivity Date Rev Description					
Rev	29-Jan-2014	29-Apr-2014	Initial Release			

Analog Devices, Inc.

DocId:2699 Parent DocId:None Layout Rev:7

QUALIFICATION PLAN / STATUS					
Test	SPECIFICATION	SAMPLE SIZE	RESULTS		
Temperature Cycle (TC)*	JEDEC <i>JESD22-A104</i>	3 lots, 32/lot	In-process. Expected completion: Jan. 2014		
Unbiased HAST (UHST)*	JEDEC JESD22-A118	3 lots, 32/lot	Pass		
High Temperature Storage Life (HTSL)	JEDEC JESD22-A103	1 lot, 32/lot	Pass		
Electrostatic Discharge Field-Induced Charged Device Model	JEDEC JESD22-C101	3/voltage	Pass ±500V		

^{*}Preconditioned per JEDEC/IPC J-STD-020

Analog Devices, Inc. PCN Material Report (Proprietary Information)								
Existing Material		Mate	erial Added	Material Removed				
GENERICNUMBER	MATERIALNUMBER	rial Ma		GENERICNUMBER	MATERIALNUMBER			